

Single Unbuffered Inverter NL17SZU04A

The NL17SZU04A is a single unbuffered inverter in tiny footprint packages.

Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- 2.1 ns t_{PD} at $V_{CC} = 5 \text{ V (typ)}$
- Input Overvoltage Tolerant up to 5.5 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 12 mA at 3.0 V
- Available in SC-88A, SOT-553 and SOT-953 Packages
- Chip Complexity < 100 FETs
- -Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



Figure 1. Logic Symbol

MARKING DIAGRAMS



SC-88A (SOT-353) DF SUFFIX **CASE 419A**





SOT-553 XV5 SUFFIX **CASE 463B**





SOT-953 **P5 SUFFIX** CASE 527AE



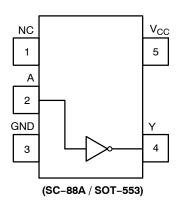
X, XX = Specific Device Code = Date Code* M

= Pb-Free Package (Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 7 of this data sheet.



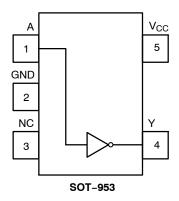


Figure 2. Pinout (Top View)

PIN ASSIGNMENT (SC-88A/SOT-553)

Pin	Function
1	NC
2	Α
3	GND
4	Y
5	V _{CC}

PIN ASSIGNMENT (SOT-953)

Pin	Function
1	Α
2	GND
3	NC
4	Y
5	V _{CC}

FUNCTION TABLE

Input	Output Y = Ā
Α	Υ
L	Н
Н	L

MAXIMUM RATINGS

Symbol	Characteristics		Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +6.5	V
V _{IN}	DC Input Voltage		-0.5 to +6.5	V
V _{OUT}	DC Output Voltage		-0.5 to V _{CC} + 0.5	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
I _{OK}	DC Output Diode Current		±50	mA
I _{OUT}	DC Output Source/Sink Current	±50	mA	
I _{CC} or I _{GND}	DC Supply Current per Supply Pin or Ground Pin	±100	mA	
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 secs		260	°C
TJ	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance (Note 2)	SC-88A SOT-553 SOT-953	377 324 254	°C/W
P _D	Power Dissipation in Still Air	SC-88A SOT-553 SOT-953	332 386 491	mW
MSL	Moisture Sensitivity		Level 1	_
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
V _{ESD}	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	2000 1000	V
I _{Latchup}	Latchup Performance (Note 4)		± 100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Applicable to devices with outputs that may be tri-stated.
- Applicable to devices with outputs that may be the stated.
 Measured with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow per JESD51-7.
 HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.
- 4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	1.65	5.5	V
V _{IN}	DC Input Voltage	0	5.5	V
V _{OUT}	DC Output Voltage	0	V _{CC}	
T _A	Operating Temperature Range	-55	+125	°C
t _r , t _f	Input Rise and Fall Time $V_{CC} = 1.65 \text{ V to } 1.95 \text{ V} \\ V_{CC} = 2.3 \text{ V to } 2.7 \text{ V} \\ V_{CC} = 3.0 \text{ V to } 3.6 \text{ V} \\ V_{CC} = 4.5 \text{ V to } 5.5 \text{ V} \end{aligned}$	/ 0 / 0	20 20 10 5	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	T _A = 25°C		С	-55°C ≤ T	A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
V _{IH}	High-Level Input		1.65 to 1.95	0.85 V _{CC}	-	_	0.85 V _{CC}	_	V
	Voltage		2.3 to 5.5	0.80 V _{CC}	-	-	0.80 V _{CC}	-	
V _{IL}	Low-Level Input		1.65 to 1.95	-	_	0.15 V _{CC}	-	0.15 V _{CC}	V
	Voltage		2.3 to 5.5	_	_	0.20 V _{CC}	-	0.20 V _{CC}	
V _{OH}	High-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -100 \mu A$	1.65 to 5.5	V _{CC} - 0.1	V _{CC}	_	V _{CC} - 0.1	-	V
		$\begin{split} &V_{IN} = GND \\ &I_{OH} = -3 \text{ mA} \\ &I_{OH} = -4 \text{ mA} \\ &I_{OH} = -6 \text{ mA} \\ &I_{OH} = -8 \text{ mA} \\ &I_{OH} = -12 \text{ mA} \\ &I_{OH} = -16 \text{ mA} \end{split}$	1.65 2.3 2.7 3.0 3.0 4.5	1.29 1.9 2.2 2.4 2.3 3.8	1.52 2.1 2.3 2.6 2.5 4.2	- - - -	1.29 1.9 2.2 2.4 2.3 3.8		
V _{OL}	Low-Level Output Voltage	$V_{IN} = V_{IH}$ $I_{OL} = 100 \mu A$	1.65 to 5.5	-	-	0.1	-	0.1	V
		$\begin{aligned} &V_{IN} = V_{CC} \\ &I_{OL} = 3 \text{ mA} \\ &I_{OL} = 4 \text{ mA} \\ &I_{OL} = 6 \text{ mA} \\ &I_{OL} = 8 \text{ mA} \\ &I_{OL} = 12 \text{ mA} \\ &I_{OL} = 16 \text{ mA} \end{aligned}$	1.65 2.3 2.7 3.0 3.0 4.5	- - - -	0.08 0.2 0.2 0.24 0.26 0.31	0.24 0.3 0.4 0.4 0.55 0.55		0.24 0.3 0.4 0.4 0.55 0.55	
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	1.65 to 5.5	-	-	±0.1	-	±1.0	μΑ
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V	0	-	-	1.0	-	10	μΑ
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND	5.5	-	-	1.0	-	10	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

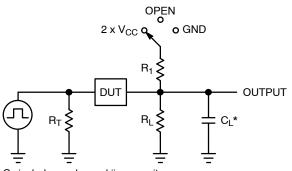
AC ELECTRICAL CHARACTERISTICS

			V _{CC}	T,	_A = 25°	С	-55°C ≤ T	_A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
t _{PLH,}	Propagation Delay, A to Y	$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	1.65 to 1.95	_	3.0	11.7	_	12.1	ns
t _{PHL}	(Figures 3 and 4)	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	2.3 to 2.7	_	2.2	6.2	_	6.5	
		$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	3.0 to 3.6	-	2.0	4.5	-	4.8	
		$R_L = 500 \Omega, C_L = 50 pF$		-	2.5	6.0	-	6.6	
		$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	4.5 to 5.5	-	1.8	3.9	-	4.1	
		R_L = 500 Ω, C_L = 50 pF		_	2.1	5.0	-	5.5	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC}	2.5	pF
C _{OUT}	Output Capacitance	$V_{CC} = 5.5 \text{ V}, V_{IN} = 0 \text{ V or } V_{CC}$	2.5	pF
C _{PD}	Power Dissipation Capacitance (Note 5)	10 MHz, V_{CC} = 3.3 V, V_{IN} = 0 V or V_{CC} 10 MHz, V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC}	9 11	pF

^{5.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.



Test	Switch Position	C _L , pF	R_L, Ω	R ₁ , Ω	
t _{PLH} / t _{PHL}	Open	See AC Characteristics Table			
t _{PLZ} / t _{PZL}	2 x V _{CC}	50	500	500	
t _{PHZ} / t _{PZH}	GND	50	500	500	

X = Don't Care

 C_L includes probe and jig capacitance R_T is Z_{OUT} of pulse generator (typically 50 $\Omega)$

f = 1 MHz

Figure 3. Test Circuit

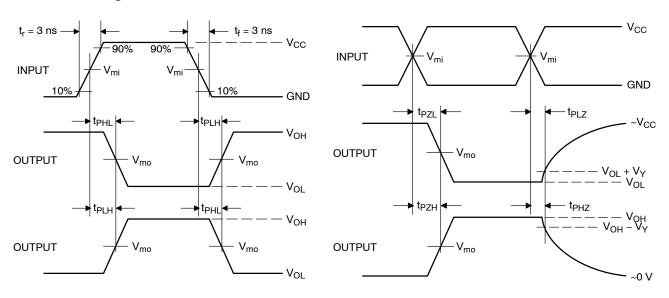


Figure 4. Switching Waveforms

		V _m		
V _{CC} , V	V _{mi} , V	t _{PLH} , t _{PHL}	t _{PZL} , t _{PLZ} , t _{PZH} , t _{PHZ}	V _Y , V
1.65 to 1.95	V _{CC} /2	V _{CC} / 2	V _{CC} / 2	0.15
2.3 to 2.7	V _{CC} /2	V _{CC} / 2	V _{CC} / 2	0.15
3.0 to 3.6	V _{CC} /2	V _{CC} / 2	V _{CC} / 2	0.3
4.5 to 5.5	V _{CC} /2	V _{CC} / 2	V _{CC} / 2	0.3

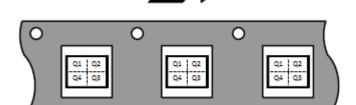
DEVICE ORDERING INFORMATION

Device	Packages	Marking	Pin 1 Orientation (See below)	Shipping [†]
NL17SZU04ADFT2G	SC-88A	L6	Q4	3000 / Tape & Reel
NL17SZU04ADFT2G-Q*	SC-88A	L6	Q4	3000 / Tape & Reel
NL17SZU04AXV5T2G	SOT-553	L6	Q4	4000 / Tape & Reel
NL17SZU04AP5T5G	SOT-953	6 (Rotated 90° CW)	Q2	8000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Pin 1 Orientation in Tape and Reel

Direction of Feed



^{*-}Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

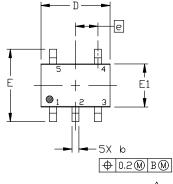
PACKAGE DIMENSIONS

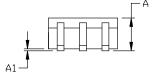
SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

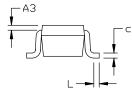
NDTES:

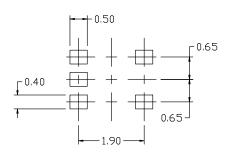
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. 419A-01 DBSOLETE, NEW STANDARD 419A-02
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
 PROTRUSIONS, OR GATE BURRS.MOLD FLASH, PROTRUSIONS,
 OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

DIM	MI	MILLIMETERS				
ויונע	MIN.	N□M.	MAX.			
А	0.80	0.95	1.10			
A1			0.10			
A3		0,20 REF	-			
b	0.10	0.20	0.30			
C	0.10		0.25			
D	1.80	2.00	2.20			
Е	2.00	2.10	2.20			
E1	1.15	1.25	1.35			
е	0.65 BSC					
L	0.10	0.15	0.30			









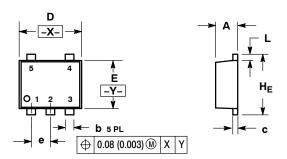
RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the IDN Semiconductor Soldering and Mounting Techniques Reference Manual, SILDERRM/D.

PACKAGE DIMENSIONS

SOT-553, 5 LEAD

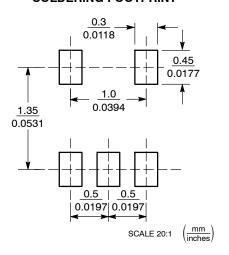
CASE 463B ISSUE C



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETERS
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
 THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM
 THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
С	0.08	0.13	0.18	0.003	0.005	0.007
D	1.55	1.60	1.65	0.061	0.063	0.065
E	1.15	1.20	1.25	0.045	0.047	0.049
е	0.50 BSC			0.020 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
HE	1.55	1.60	1.65	0.061	0.063	0.065

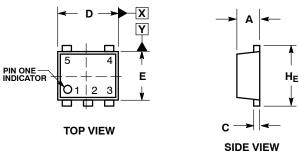
SOLDERING FOOTPRINT*

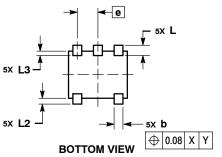


*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOT-953 CASE 527AE ISSUE E





- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

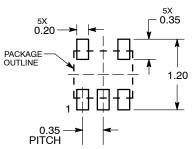
 2. CONTROLLING DIMENSION: MILLIMETERS

 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.

 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS					
DIM	MIN	NOM	MAX			
Α	0.34	0.37	0.40			
b	0.10	0.15	0.20			
С	0.07	0.12	0.17			
D	0.95	1.00	1.05			
E	0.75	0.80	0.85			
е	0.35 BSC					
HE	0.95	1.00	1.05			
L	0.175 REF					
L2	0.05	0.10	0.15			
L3			0.15			

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales